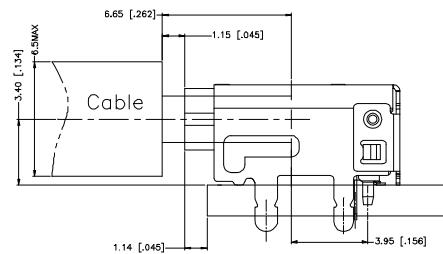
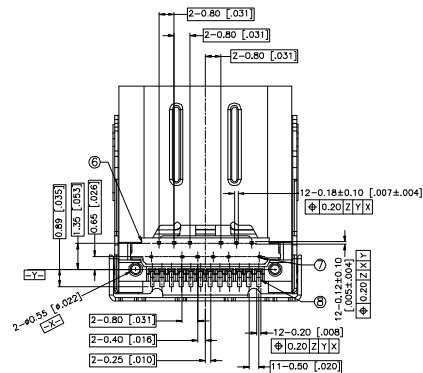
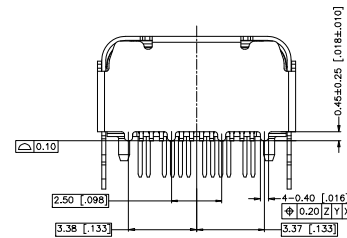
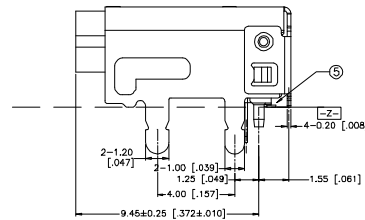
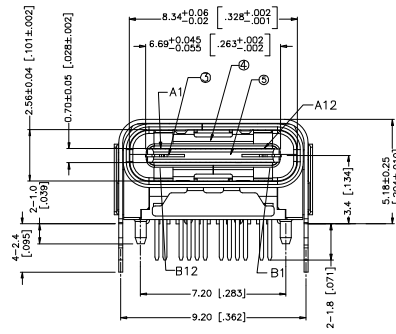
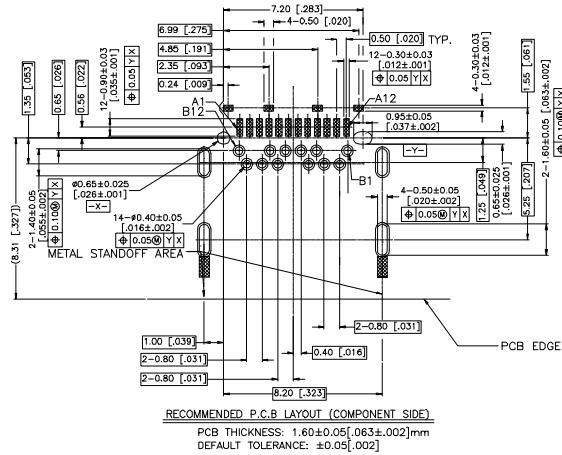
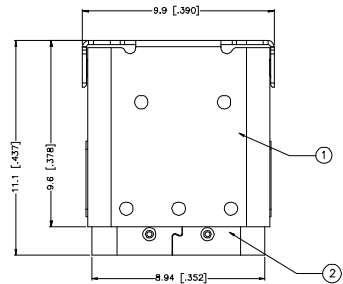


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2017/03/14	Phebe Su
A1			Change shell type	2017/08/02	Summer Wang



NOTES:

1.MECHANICAL:

- 1.INSERTION: 5-20N .
- 2.EXTRACTION: 8-20N UP TO 1000 MATING.
6~20 N AFTER 1000 DURABILITY CYCLES
- 3.DURABILITY: 10000 CYCLES
- 4.OPERATING TEMPERATURE: -55°C ~ +85°C

2.ELECTRICAL:

1. CONTACT CURRENT RATING:
VBUS AND GND CONTACTS RATED AT 1.25A EA.,
PARALLELED FOR A TOTAL OF 5A
2. LOW LEVEL CONTACT RESISTANCE:
40 MILLIOHMS MAX. FOR VBUS ,GND AND OTHER CONTACTS.
50 MILLIOHMS MAX. AFTER ENVIRONMENT TEST.
3. DIELECTRIC WITHSTANDING VOLTAGE: 100VAC (RMS) MIN
4. INSULATION RESISTANCE: 100 Megohms MIN.

MATRIX PART NO:

MUSB12-30-211

MATRIX USB

Pin Number

- Series number

— Plating
01:Gold Flash
15:15u"
30:30u"

⑨	UPPER CONTACT	12	C7025R-EH	30u"+Pd/Ni+G/F PLATING ON CONTACT AREA,MAT TIN 120u" MIN. PLATING ON SOLDER TAILS AREA,80u" MIN. NICKEL UNDERPLATING OVER ALL
⑧	LOWER CONTACT	12		
⑦	LOWER IM	1	LCP UL 94V-0	MOLDED COLOR: BLACK.
⑥	UPPER IM	1	LCP UL 94V-0	MOLDED COLOR: BLACK.
⑤	CENTER IM	1	LCP UL 94V-0	MOLDED COLOR: BLACK.
④	EMC	1	SUS304-1/2H	CLEAN
③	SHIELD PLATE	1	SUS304-1/2H	NICKEL PLATING OVER ALL.
②	INNER SHELL	1	SUS304-1/2H	CLEAN
①	OUTER SHELL	1	SUS304-1/2H	NICKEL PLATING ONLY AT TAIL, Au AT TABS AND SOLDER TAIL.
NO.	DESCRIPTION	QTY.	MATERIAL	TREATMENT



Matrix Electronics Co.,Ltd

TOLERANCE: X. ±0.38 X.X ±0.25 X.XX ±0.15 X.XXX ±0.10 ANGLE: ±3°		DESIGN BY : Summer Wang	DATE : 2017/08/02	PART NAME: USB 3.1 Gen 2 Type C Female R/A, Pad type, CL 3.4	
		CHECKED BY: Vicky Hsieh	DATE : 2017/08/02	PART NO.	MUSB12-30-211
		APPROVED BY1: Richard Hsieh	DATE : 2017/08/02	MOLD NO.	NA
UNIT: mm [inch]		APPROVED BY2:	DATE :	DRAW NO.	
SCALE: 1:1	SIZE: A4	Richard Hsieh	2017/08/02	SHEET NO.	1 OF 1